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preleaded and postleaded carriers. The preleaded carriers have copper alloy or Kovar leads that are attached by the manufacturer. In postleaded carriers, the user attaches the leads to the castellations of the leadless ceramic chip carriers. When leaded ceramic packages are used, their dimensions are generally the same as in plastic leaded chip carriers. Ceramic Leaded Chip Carrier (PLCC) Active SMT Components (Plastic Packages) As discussed above, ceramic packages are expensive and are used primarily for military applications. Plastic SMD packages, on the other hand, are most widely used packages for nonmilitary applications, where hermiticity is not required. The ceramic packages have solder joint cracking due to CTE mismatch between the package and the substrate, but the plastic packages are also not trouble free. Here are all the Active SMD Components (Plastic Packages): Small Outline Transistors (SOT) Small Outline Transistors are one of the forerunners of active devices in surface mounting. They are three- and four-lead devices. The three-lead SOTs are identified as SOT 23 (EIA TO 236) and SOT 89 (EIA TO 243). The four-lead device is known as SOT 143 (EIA TO 253). These packages are generally used for diodes and transistors. The SOT 23 and SOT 89 packages have become almost universal for surface mounting small transistors. Even as the use of high pin count complex integrated circuits is becoming widespread, the demand for various types of SOTs and SODs continue to grow. Small Outline Transistors (SOT) Small Outline Integrated Circuit (SOIC and SOP) The small outline integrated circuit (SOIC or SO) is basically a shrink package with leads on 0.050 inch centers. It is used to house larger integrated circuits than is possible in SOT packages. In some cases, SOICs are used to house multiple SOTs. SOIC contains leads on two sides that are formed outward in what is generally called gull wing lead. SOICs need to be handled carefully to prevent lead damage. SOICs come in mainly two different body widths: 150 mil 300 mils. The body width of packages having fewer than 16 leads is 150 mil; for more than 16 leads, 300 mil widths is used. The 16 lead packages come in both body widths. Small Outline Integrated Circuit (SOIC and SOP) Plastic Leaded Chip Carriers (PLCC) The plastic leaded chip carrier (PLCC) is a cheaper version of ceramic chipcarrier. The leads in PLCC provide the compliance needed to take up the solder joint stress and thus prevent solder joint cracking. PLCCs with large die-to-package ratios may be susceptible to package cracking due to moisture absorption. They need proper handling. Plastic Leaded Chip Carriers (PLCC) Small Outline J Packages (SOJ) The SOJ packages have J-bend leads like PLCC, but they have pins on only two sides. This package is a hybrid of SOIC and PLCC and combines the handling benefits of PLCC and space efficiency of SOIC. SOJs are commonly used for high density (1, 4, and 16 MB) DRAMs. Small Outline J Packages (SOJ) Fine Pitch SMD Packages (QFP, SQFP) SMD packages with very fine pitch and larger number of leads are called fine pitch package. Quad flat pack (QFP) and shrink quad flat pack (SQFP) are examples of fine pitch package. Fine pitch packages have thinner leads and require a thinner land pattern design. Fine Pitch SMD Packages (QFP, SQFP) Ball Grid Array (BGA) SMD Components BGA or Ball Grid Array is an array package like PGA (pin grid array) but without the leads. There are various types of BGAs, but the main categories are ceramic and plastic BGA. The ceramic BGAs are called CBGA (Ceramic Ball Grid Array) and CCGA (Ceramic Column Grid Array), and the plastic BGAs are referred to as PBGA. There is another category of BGA known as tape BGA (TBGA). The ball pitches have been standardized at 1.0, 1.27, and 1.5 mm pitch. (40,50, and 60 mil pitch). The body sizes of BGAs vary from 7 to 50 mm and their pin counts vary from 16 to 2400. Most common BGA pin counts range between 200 and 500 pins. BGAs are very good for self alignment during reflow even if they are misplaced by 50% (CCGA and TBGA do not self align as well as PBGAs and CBGAs do). This is one reason for the higher yield with BGAs. Ball Grid Array (BGA) How to Identify SMD Components SMDs don't have any visible leads like their through-hole counterparts. They are rather marked with with cryptic codes. You can adopt different methodology to identify these small SMD components - Physical appearance (Shape, Size), SMD code, use SMD Tester or a Multimeter or Refer to Online Database. Let us learn in some detail as to how to identify SMD components efficiently. 1. Identify SMD Components from Appearances Observe the Package Type. Different SMD components have unique package shapes and sizes. Common types include: Resistors: Rectangular in shape with three or four-digit codes. Example - 0402, 0603, 0805. Capacitors: Similar in shape to resistors but may not have any markings. Example - 0603, 0805, 1206 Diodes: Marked with polarity bands. Example - SOD-123, SOT-23 Transistors and ICs: Feature multiple pins and sometimes have identification codes. Transistors Example - SOT-23, SOT-223. ICs Example - QFP, BGA, SOIC 2. Identify by Component Code SMD components are generally marked with alphanumeric codes. You can refer to the datasheet or SMD code book to identify and determine the type and value of the component. 3. Use a SMD Component Tester or a Multimeter You can use Smart SMD Tester that can easily help you to accurately identify component types and characteristics (capacitance, resistance, and diodes). Alternatively, you can also use a digital multimeter to test and verify values of resistors, capacitors, diodes, and transistors. 4. Refer to Datasheet and Online Database Most major electronic components manufacturers in the world provide detailed specifications for all the SMD components they manufacture or supply. You can refer to their official website or third party websites that host Datasheet Archive of most SMD Components. Common SMD Components and Identification Methods Component Package Example Identification Method Resistor 0402, 0603, 0805 Printed value code (e.g., 103 = 10kΩ) Capacitor 0603, 0805, 1206 No marking, use Smart Tweezers Diode SOD-123, SOT-23 Polarity band, part number Transistor SOT-23, SOT-223 Manufacturer marking, pin count IC QFP, BGA, SOIC P/N on top Video: Types of SMD Components List and Identification Conclusion We hope this comprehensive guide with pictures and videos helped you to understand different types of SMD components and how to identify SMD components from appearance, by reading SMD codes, component markings, and by using testing tools like a smart SMD tester or a digital multimeter. Please do share your thoughts and ideas in comment below. Thanks! FAQs: SMD (Surface Mounted Devices) SMD components (Surface Mount Device Components) are electronic parts used in PCB circuit assembly. Unlike traditional through-hole components, SMD components are soldered directly onto the surface of a circuit board. They are smaller, more compact, and allow for automated assembly processes. SMD components offer several advantages: They save space on circuit boards, enabling higher component density. They also facilitate automated assembly, reducing production costs. SMD components have better high-frequency performance due to shorter lead lengths and less parasitic effects. Additionally, their smaller size supports miniaturization in electronic devices. SMD components are soldered using reflow soldering. The process involves applying solder paste to the pads on the circuit board, placing the SMD components on top of the paste, and then heating the board in a reflow oven. The solder paste melts, creating a secure electrical and mechanical connection between the components and the board. There are various types of SMD components, including: Resistors: Passive components that limit current flow. Capacitors: Store and release electrical energy. Diodes: Allow current to flow in one direction only. Transistors: Control current or amplify signals. Integrated Circuits (ICs): Complex electronic functions in a single package. While SMD components offer numerous benefits, there are challenges to consider. Their small size makes manual soldering difficult without specialized tools. SMD components can also be more sensitive to heat during soldering, potentially leading to thermal damage. Additionally, troubleshooting and repair can be more complex due to the densely packed nature of SMD PCB assemblies. Related Articles: